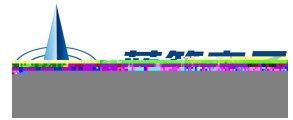


A	2018-8				
A	2020-2-17	2	80A 0.9V, 0.05mA 1mA	100A, °C °C SS315C	0.95V 0.3mA 3mA
B	2021-2-9	7			



150V

3.0A

:

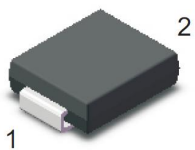
□

□

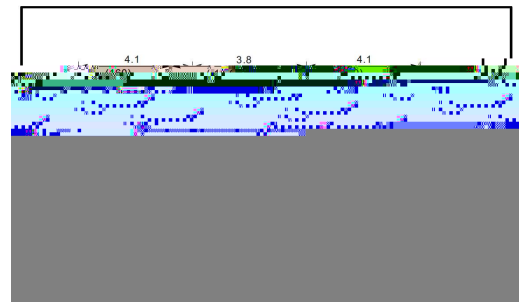
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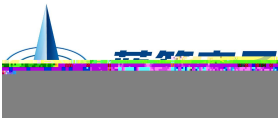
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□ □



The recommended mounting pad size





参数	符号	数值	单位
	()		
			℃
			℃
			℃

)

)

参数	符号	测试条件	数值	单位
		℃		
		℃		

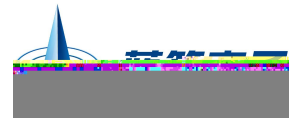


Fig. 4 Forward Current Derating Curve

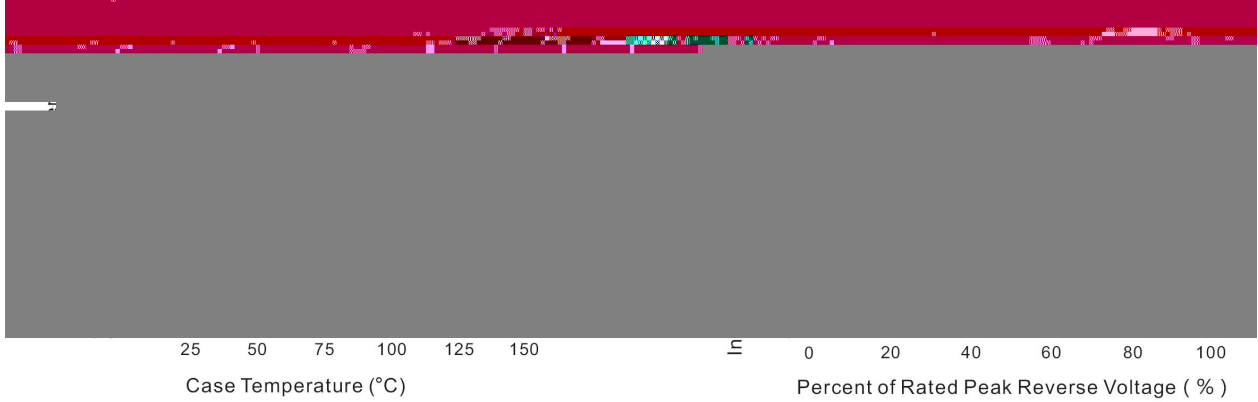


Fig. 3 Typical Reverse Current vs. Voltage

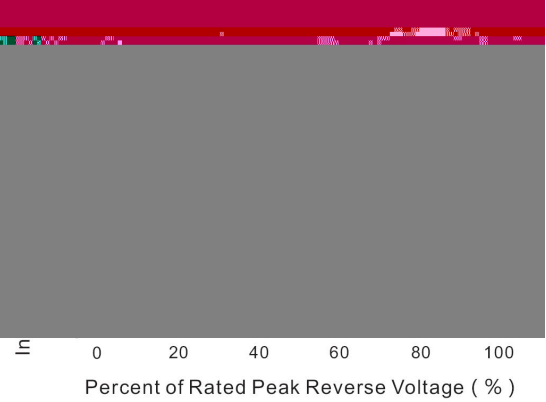


Fig. 3 Typical Forward Characteristic

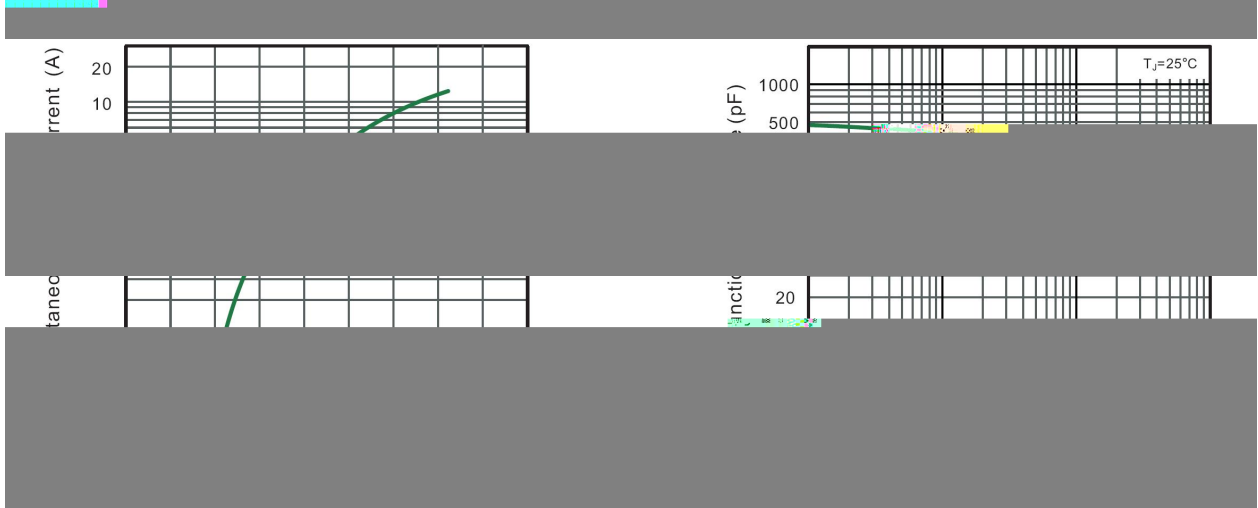


Fig. 5 Maximum Non-Repetitive Peak

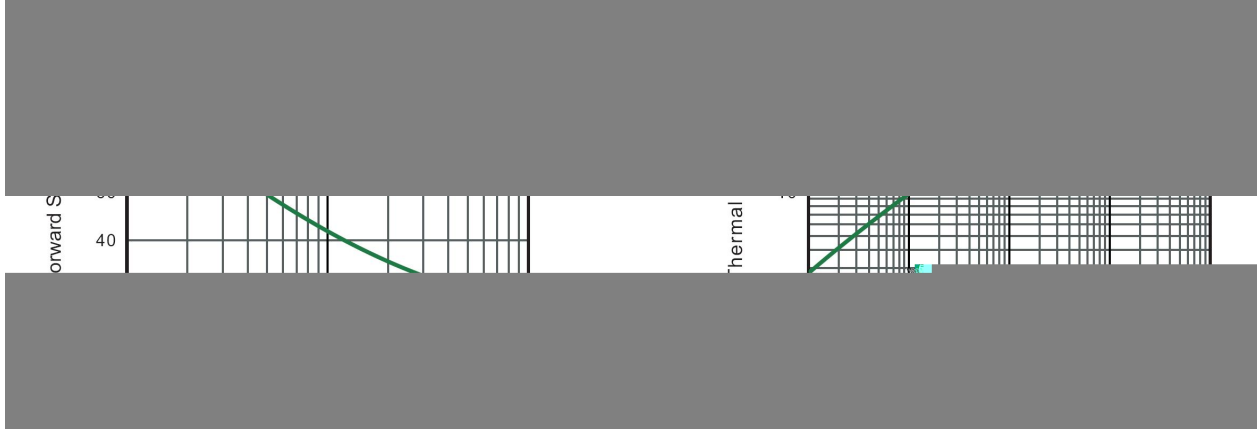
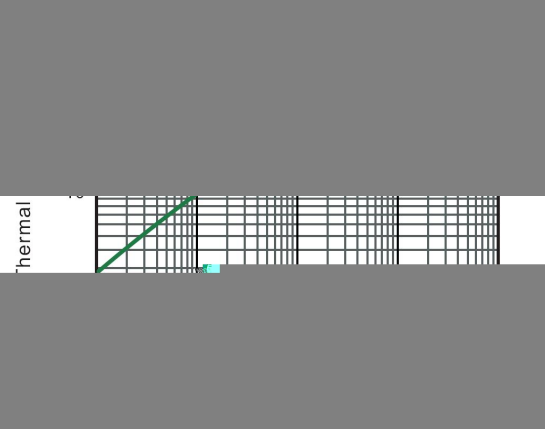
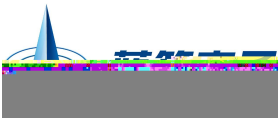
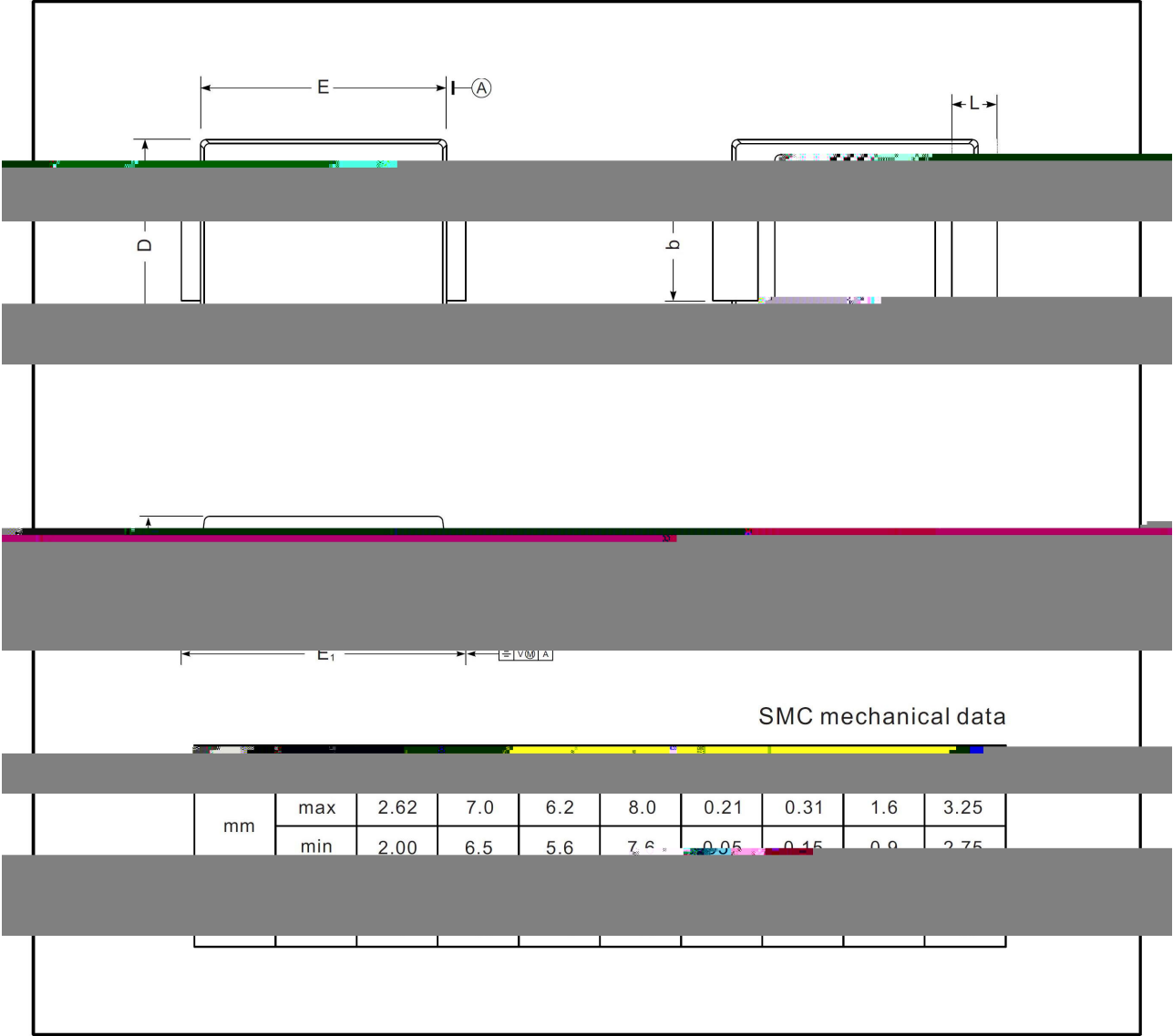


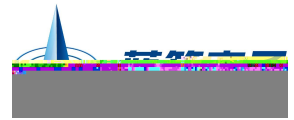
Fig. 6 Typical Transient Thermal





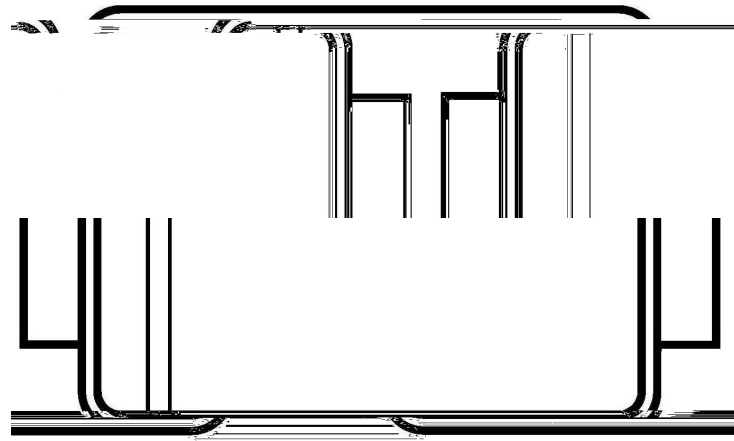
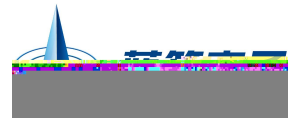
SMC





Marking

Type number	Marking code
SS315C	SS315



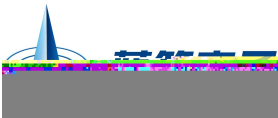
说明

： 为型号代码

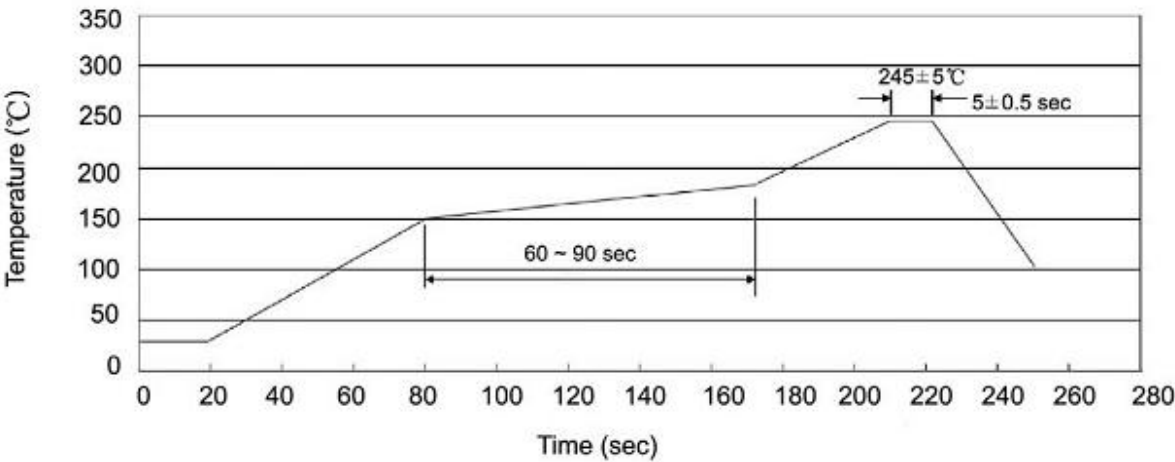
FFFF 为生产批号追溯码，第 个 为年月代码，后面 个 为当月小批号代码

：

。



Temperature Profile for IR Reflow Soldering(Pb-Free)



± °C ± °C ± °C ± °C

± °C ± ± °C ±

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
						"		